

**IN THE CLAIMS**

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 39 and 44. The specific amendments to individual claims are detailed in the following marked up set of claims.

39.) (Thrice Amended) A method of attaching a semiconductor die to an organic support structure, comprising:

(*corrected*) (affixing) a first side of a two-sided adhesive tape to a surface of the organic support structure, wherein adhesive of the adhesive tape comprises a [pressure sensitive,] hybrid material of thermoplastic and thermosetting adhesive;

elevating the temperature to 100 degrees C to activate the first side of the adhesive tape;

applying pressure to the tape and organic support structure to laminate the adhesive tape to the organic support structure;

affixing a face of the semiconductor die to a second side of the adhesive tape;

elevating the temperature of the tape to activate the second side of the adhesive tape; and

applying pressure to the die and organic support structure to laminate the adhesive tape to the die.

44.) (Thrice Amended) A method of attaching a semiconductor die to an organic support structure, comprising:

(affixing) a first side of a two-sided adhesive tape to a surface of the organic support structure, wherein adhesive of the adhesive tape comprises a [pressure sensitive,] hybrid material of thermoplastic and thermosetting adhesive;

elevating the temperature of the tape to activate the first side of the adhesive tape;

applying pressure to the tape and organic support structure to laminate the adhesive tape to the organic support structure, wherein elevating the temperature and applying pressure occurs

for 100ms;

affixing a face of the semiconductor die to a second side of the adhesive tape;

elevating the temperature of the tape to activate the second side of the adhesive tape;

applying pressure to the die and organic support structure to laminate the adhesive tape to the die;

wire bonding bond wires to a plurality of bond pads on the die face with a plurality of lead connections on the organic support structure;

applying an encapsulating material over the bond pads, bond wires, lead connections, and a portion of the die face and support structure.

#### **REMARKS**

Applicant has carefully reviewed and considered the Office Action mailed on April 9, 2002, and the Advisory Office Action mailed July, 8, 2002. Claims 39 and 44 are amended such that claims 34-63 are now pending in this application.

#### **Objection to the Disclosure**

The disclosure was objected to because of the use of the term "thermoset" at page 10, lines 10 and 11. Applicant has amended the specification in accordance with the suggestion made by the Examiner in paragraph 1 of the Final Office Action. Withdrawal of the objection is respectfully requested.

#### **§102 Rejection of the Claims**

Claims 34, 37-38 and 51-63 were rejected under 35 USC § 102 (e) and (b), respectively as being anticipated by or, in the alternative, under USC 103 (a) as obvious over either King or Bradley. Applicant hereby incorporates by reference all arguments relating to this rejection that were made in the Amendment and Response Under 37 CFR § 1.111 which was mailed October 17, 2001. Applicant respectfully traverses the rejection since the cited art fails to establish all of